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	R SHEET  Y  Please record the attached documents or the new address(es) below.  2. Name and address of receiving party(ies)
. Name of conveying party(ies)	2. Name and address of receiving party(ies)
oung-dae Kim	Name: Samsung Electronics Co., Ltd.
Dae-young Kim	Internal Address:
Iditional name(s) of conveying party(ies) attached? Yes	
Nature of conveyance/Execution Date(s):	Street Address: _416, Maetan-dong,
Execution Date(s) September 27, 2006  Morgan	Yeongtong-gu
/ Assignment	City: _Suwon-si, Gyeonggi-do
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Joint Research Agreement	State:
Government Interest Assignment	Country:_ Republic of KoreaZip:
Executive Order 9424, Confirmatory License	
OtherOther	Additional name(s) & address(es) attached?
Additional numbe	ers attached? Yes No  6. Total number of applications and patents
oncerning document should be mailed:	involved: 1
Name: Steven M. Mills	7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00
nternal Address:	Authorized to be charged by credit card
	Authorized to be charged to deposit account
treet Address: Mills & Onello LLP	✓ Enclosed
Eleven Beacon Street, Suite 605	None required (government interest not affecting title)
ity: Boston	8. Payment Information
	a. Credit Card Last 4 Numbers
tate: Massachusetts Zip: 02108	Expiration Date
hone Number: (617) 994-4900	b. Deposit Account Number
ax Number:_(617) 742-7774	Authorized User Name
Email Address: mail@millsonello.com	
. Signature: See Will Co	/o/4/06 Date
Signature  Steven M. Mills Registration No. 36,610	Total number of pages including cover
Name of <b>\</b> Person Signing	one of a consider to

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to: Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

Reference No.; SAM-1013

## ASSIGNMENT

We, Young-dae Kim, of 102-303, Hyundai Apt., Pungnap 2-dong, Songpa-gu, Seoul, Republic of Korea; and Dae-young Kim, of 302-1103, Sarabu Renaissance Apt., Gwongok-dong, Asan-si, Chungcheongnam-do, Republic of Korea, having invented improvements in WAFER STRUCTURE WITH MIRROR SHOT described in an application for Letters Patent of the United States, executed by us on even date herswith, for good and valuable consideration, receipt of which is hereby acknowledged from Samsung Electronics Co., Ltd., a Korean corporation having a place of business at 416, Maetandong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea (and hereinafter called the Assignee, which term shall include its successors and assigns), do hereby sell, assign and transfer unto the Assignee our entire right, title, and interest in and throughout the United States of America (including its territories and dependencies) and all countries foreign thereto, in and to and under said application (which term shall include hereinafter where the context so admits all divisional, continuing, reissue and other patent applications based thereon) and the inventions (which term shall include each and every such invention, or part thereof) therein described, and any and all patents and like rights of exclusion (including extensions thereof) of any country which may be granted on or for said inventions or on said application;

And for the same consideration We do also hereby sell, assign, and transfer unto the Assignee, all our rights under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, and all other treaties of like purpose in respect of said inventions and said application, and We do hereby authorize the Assignee to apply in our name or its own name or its designee for patents and like rights of exclusion on or for said inventions in all countries, claiming (if the Assignee so desires) the priority of the filing date of said application under the provisions of said Convention, Treaty or any such other Convention or Treaty;

And for the same consideration, We do hereby agree for ourselves and for our heirs, executors, and administrators, promptly upon request of the Assignee to execute and deliver without further compensation any power of attorney, assignment, original, divisional, continuing, reissue or other application or applications for patent or patents or like rights of exclusion of any country, or other lawful documents and any further assurances that may be deemed necessary or desirable by the Assignee, fully to secure to it said right, title, and interest as aforesaid in and to said inventions, applications, and said several patents and like rights of exclusion (including extensions thereof) or any of them, all, however, at the expense of the Assignee, its successors, or assigns;

And We do hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America and the corresponding Official of each country foreign thereto to issue to the Assignee, any and all patents and like rights of exclusion which may be granted in any country upon said United States application on or for said inventions;

And We do hereby covenant for ourselves and our legal representatives and agree with the Assignes, that We have granted no right or license to make, use, or sell said inventions to anyone except the Assignee, that prior to the execution of this deed our right, title, and interest in and to said inventions has not been otherwise encumbered by us, and that We have not executed and will not execute any instruments in conflict herewith.

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PATENT REEL: 018394 FRAME: 0067

## Reference No.: SAM-1013

First or Sole Inventor:

Signature:

Young-due Kim Date: 27/48/06

Second Joint Inventor:

Signature:

REFERENCE NO.: 8AM-1013

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**PATENT REEL: 018394 FRAME: 0068** 

**RECORDED: 10/04/2006**